

REMARKS

Claims 9-13 and 28-32 are pending. Claims 9 and 12 are amended to recite “a metal-containing layer” instead of “a seed layer of metal”. Claims 28-32 are added. Claims 28 and 31 are added to recite “wherein the metal-containing layer includes a seed layer and a barrier layer.” These features are supported at least on page 8, lines 5-10 of the current specification. Claims 29 and 32 are added to recite “wherein the barrier layer at least one of tantalum, tantalum nitride, titanium nitride, and tungsten nitride.” These features are supported at least on page 8, lines 5-10 of the current specification. Claim 31 is added to recite “A dual damascene process comprising: providing a dielectric layer; patterning and etching said dielectric layer to form a trench having a bottom surface, a mouth, and side walls; depositing a barrier layer to coat the dielectric layer; said bottom surface, and said side walls; depositing a metal-containing layer over the barrier layer; reducing the metal-containing layer by an amount to remove any overhang present at the mouth of the trench; and filling the trench.” These features are supported at least on page 8, line 1 to page 9, line 10 of the current specification. No new matter is added as a result of the above amendments. Reconsideration of the claims is respectfully requested in light of the above amendments.

The Examiner is invited to call the undersigned at the below-listed telephone number if in the opinion of the Examiner such a telephone conference would expedite or aid the prosecution and examination of this application.

Respectfully submitted,

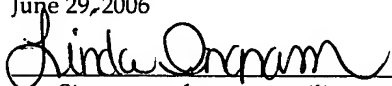


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<p>I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner For Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on: June 29, 2006</p> <p> Signature of person mailing paper and fee</p>
